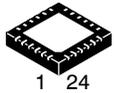


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

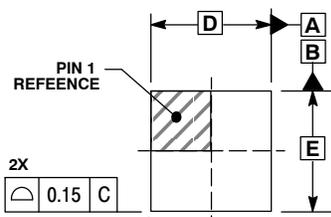


1 24

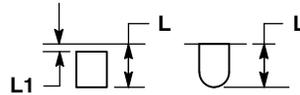
SCALE 2:1

QFN24, 4x4, 0.5P
CASE 485L
ISSUE B

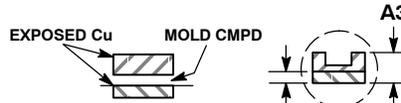
DATE 05 JUN 2012



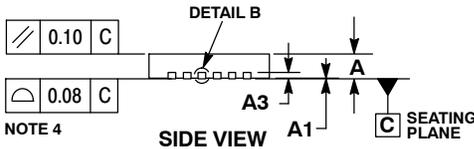
TOP VIEW



DETAIL A
ALTERNATE
CONSTRUCTIONS



DETAIL B
ALTERNATE TERMINAL
CONSTRUCTIONS



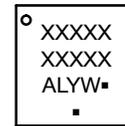
SIDE VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	4.00	BSC
D2	2.70	2.90
E	4.00	BSC
E2	2.70	2.90
e	0.50	BSC
L	0.30	0.50
L1	0.05	0.15

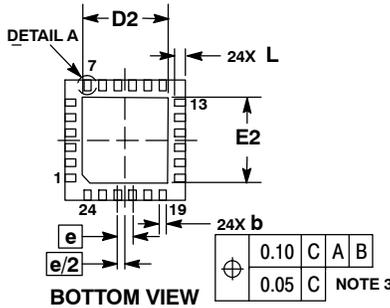
GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

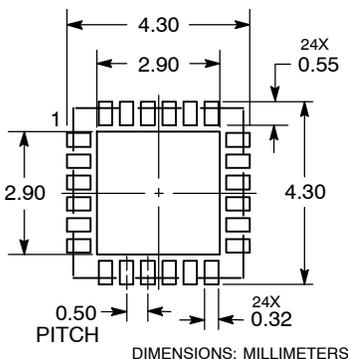
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN24, 4X4, 0.5P	PAGE 1 OF 2

